

**Access Hole:**

A hole in a layer of dielectric material that provides access to a land on a conductive layer of the flexible circuit.

**Adhesions (pressure sensitive tape):**

The bond produced by contact between pressure-sensitive adhesive and a surface.

**Adhesive:**

A substance such as glue or cement used to fasten objects together.

**Array:**

A group of elements or circuits arranged in rows and columns on a panel.

**Artwork:**

An accurately-scaled configuration that is used to produce the conductor pattern.

**Base Material:**

The insulative material upon which a conductive pattern may be formed. The base material may be rigid or flexible, or both.

**Bend Ratio:**

A relationship between the thickness of material bent to the radius over which it is bent.

**Bending Resistance:**

The ability of a material to withstand repeated bending to specified parameters without producing cracks or breaks in excess of the specification allowance.

**Bonding Layer:**

An adhesive layer used in bonding together plies of dielectric and conductive materials during lamination.

**Cap Lamination:**

A process of making multilayer printed boards with surface layers of metal-clad laminates bonded in a single operation.

**Conductor Layer:**

The total conductive pattern formed on one side of a single layer of base material.

**Coverfilm (Coverlayer):**

A film of dielectric material with adhesive which is bonded over the etched conductor runs to insulate them.

**Dielectric Strength:**

The maximum voltage that a dielectric can withstand under specified conditions without resulting in a voltage breakdown, usually expressed as volts per unit of dimension.

**Dynamic Flex:**

A flexible circuit designed to move during operation.

**Edge Spacing:**

The distance of an etched feature from the edges of a printed board.

**Flexible Multilayer Printed Board (Type 3):**

Multi-layered printed board made of only flexible materials. Different areas of the multilayer printed board may have different numbers of layers and thickness.

**Flexible Printed Board (Circuit):**

A printed board made only of flexible materials.

**Insulation Resistance:**

The electrical resistance of an insulating material that is determined under specific conditions between any pair of contacts, conductors or grounding devices in various combinations.

**Polyimide:**

The synthetic polymer that has more than two imide radicals in the main chain.

**Prepreg:**

A sheet of material that has been impregnated with a resin cured to an intermediate stage (i.e. B-staged resin).

**Sequential Lamination:**

The process of manufacturing multilayer printed circuit boards in which multiple double-sided layer stacks with interconnecting holes between conductive patterns on both sides are laminated or combined, after which additional layers are attached to the partially completed board stack up.

**Static Flex (Flex-To-Install):**

A flexible printed board designed to be bent for installation purposes only (not in operation).

**Steel Rule Die:**

A piece of tooling made from a hardwood base with hand-formed steel rule placed into a laser burned path which is used to profile portions of or the entire final shape of a flex circuit.

**Stiffener Board:**

A material fastened to the surface of a flexible printed board to increase its mechanical strength.

**Thermal Cure:**

A chemical reaction using heat energy that hardens organic substances such as adhesives and coating materials.

**Window (in the coverlayer):**

An opening in the dielectric of a flexible printed board that exposes conductors.